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Maxim Integrated MAX4885EEVKIT+

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# **Ultra-Low Capacitance 1:2 VGA** Switch with ±15kV ESD

## **General Description**

The MAX4885E integrates high-bandwidth analog switches and level-translating buffers to implement a complete 1:2 multiplexer for VGA signals. The device provides switching for RGB, display data channel (DDC).

Horizontal and vertical synchronization (HSYNC/VSYNC) inputs feature level-shifting buffers to support low-voltage CMOS or standard TTL-compatible graphics controllers, meeting the VESA requirement of ±8mA. DDC, consisting of SDA\_ and SCL\_, is a bidirectional activelevel translating switch that reduces capacitive load. The MAX4885E features high ESD protection to ±15kV Human Body Model (HBM) on all twelve externally routed terminals. See the Pin Description section. All other pins are protected to ±10kV Human Body Model (HBM).

The MAX4885E is specified over the extended -40°C to +85°C temperature range, and is available in the 24-pin, 4mm x 4mm TQFN package.

## **Applications**

Notebook Computers/Docking Stations **Digital Projectors Computer Monitors** Servers/Storage

**KVM Switches** 

#### **Features**

- ♦ ±15kV HBM ESD Protection on Externally Routed **Terminals**
- ♦ 1GHz Bandwidth
- ♦ Low 5Ω (typ) On-Resistance (R, G, B Signals)
- ♦ Low 6pF (typ) On-Capacitance (R, G, B Signals)
- ♦ Low R, G, B Skew -50ps (typ)
- ♦ Near Zero Power Consumption (< 2μA)
- ♦ Ultra-Small, 24-Pin (4mm x 4mm) TQFN Package

#### **Ordering Information**

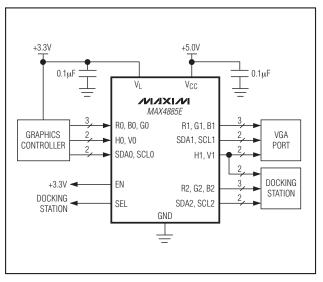
PART	TEMP RANGE	PIN-PACKAGE
MAX4885EETG+	-40°C to +85°C	24 TQFN-EP*

<sup>\*</sup>EP = Exposed pad.

### Pin Configuration

#### TOP VIEW G2 B1 5 18 17 | 16 | 15 | 14 | 13 SCL<sub>2</sub> 12 V1 19 H1 SCL<sub>1</sub> SDA2 10 GND MIXIM MAX4885E 9 SDA1 $V_{\mathsf{L}}$ 22 ΕN 23 8 $V_{CC}$ SEL V0 24 8 TOFN-EP \*EXPOSED PAD. CONNECTED TO GROUND OR LEAVE UNCONNECTED.

## **Typical Operating Circuit**



MIXIM

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<sup>+</sup>Denotes lead-free package/RoHS-compliant package.



#### **ABSOLUTE MAXIMUM RATINGS**

(All voltages referenced to GND.)	
V <sub>CC</sub> , V <sub>L</sub> 0.3	V to +6V
R_, G_, B_, SDA1, SCL1, SDA2, SCL2,	
H1, V1, (Note 1)0.3V to V <sub>C</sub>	C + 0.3V
H0, V0, SDA0, SCL0, EN, SEL0.3V to V	L + 0.3V
Continuous Current through RGB Switches	±30mA
Continuous Current through DDC Switches	±30mA
Peak Current through RGB Switches	
(pulsed at 1ms, 10% duty cycle)	±90mA
Peak Current through DDC Switches (pulsed at 1ms,	
10% duty cycle)	±90mA

Continuous Power Dissipation (T <sub>A</sub> = +70°C) 24-Pin TQFN (derate 27.8mW/°C above +70°C)2222mW
Junction to Ambient Thermal Resistance (θ <sub>JA</sub> ) (Note 2)
24-Pin TQFN36°C/W
Junction to Ambient Thermal Resistance (θ <sub>JC</sub> ) (Note 2)
24-Pin TQFN3°C/W
Operating Temperature Range40°C to +85°C
Storage Temperature Range65°C to +150°C
Junction Temperature+150°C
Lead Temperature (soldering, 10s)+300°C
,

- Note 1: Signals exceeding V<sub>CC</sub> or GND are clamped by internal diodes. Limit forward-diode current to maximum current rating.
- **Note 2:** Package thermal resistances were obtained using the method described in JEDEC specifications. For detailed information on package thermal considerations, refer to <a href="https://www.maxim-ic.com/thermal-tutorial">www.maxim-ic.com/thermal-tutorial</a>.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### **ELECTRICAL CHARACTERISTICS**

 $(V_{CC} = +5.0V \pm 10\%, V_L = +2V \text{ to } +5.5V, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted.}$  Typical values are at  $V_{CC} = +5.0V, V_L = +3.3V$  and  $T_A = +25^{\circ}C.)$  (Note 3)

PARAMETER	SYMBOL	CON	IDITIONS	MIN	TYP	MAX	UNITS
Was Chicagont Changle Change	1	\\\.F.0\\	EN = V <sub>L</sub>			4	
V <sub>CC</sub> Quiescent Supply Current	Icc	$V_{CC} = +5.0V$	EN = GND			1	μΑ
W. Ouissaant Cumply Current	ls a	V 2 2V	EN = V <sub>L</sub>			-1	
V <sub>L</sub> Quiescent Supply Current	lvL	$V_L = +3.3V$	EN = GND			1	μΑ
RGB ANALOG SWITCHES							
On-Resistance	Ron	V <sub>CC</sub> = +5.0V, I <sub>IN</sub> = - (Note 4)	$-10mA$ , $V_{IN} = +0.7V$		6		Ω
On-Resistance Matching	ΔRon	$0 \le V_{IN} \le 0.7V$ , $I_{IN} =$	-10mA		0.5		Ω
On-Resistance Flatness	R <sub>FLAT</sub> (ON)	$0 \le V_{IN} \le 0.7V$ , $I_{IN} =$	-10mA		0.5		Ω
Off-Leakage Current	I <sub>L</sub> (OFF)	V <sub>CC</sub> = +5.5V, V <sub>IN</sub> = V <sub>EN</sub> = 0 or V <sub>L</sub>	+0.3V or +5.5V,	-1		+1	μΑ
On-Leakage Current	I <sub>L(ON)</sub>	V <sub>CC</sub> = +5.5V, V <sub>IN</sub> = V <sub>EN</sub> = V <sub>L</sub>	+0.3V or +5.5V,	-1		+1	μA
HV BUFFER							
Input Voltage Low	VILHV					0.33 x V <sub>L</sub>	V
Input Voltage High	VIHHV			0.66 x V <sub>L</sub>			V
Input Logic Hysteresis	V <sub>H</sub> YST				75		mV
Input Leakage Current	I <sub>INHV</sub>	$V_{CC} = +5.5V$ , $V_{L} = +5.5V$ , $V_{IN} = 0$ or $V_{L}$		-1		+1	μΑ
High-Output Drive Current	Іонну	V <sub>OHHV</sub> ≥ 3.0V		8.0			mA
Low-Output Drive Current	lolhv	V <sub>OLHV</sub> ≤ 0.6V		8.0			mA

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# Ultra-Low Capacitance 1:2 VGA Switch with ±15kV ESD

### **ELECTRICAL CHARACTERISTICS (continued)**

 $(V_{CC} = +5.0V \pm 10\%, V_L = +2V \text{ to } +5.5V, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted.}$  Typical values are at  $V_{CC} = +5.0V, V_L = +3.3V \text{ and } T_A = +25^{\circ}C.)$  (Note 3)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
SDA_, SCL_						
Supply Voltage	VL		2.0		5.5	V
On-Resistance	Ron	$V_{IN} = +0.4V$ , $I_{IN} = \pm 2mA$ , $V_L = +2.0V$		10		Ω
On-Capacitance	Con	f = 100kHz		15		рF
High-Impedance Input Leakage Current	I <sub>INHIZ</sub>	EN = GND, V <sub>CC</sub> = +5.5V, V <sub>L</sub> = +3.6V, SCL0, SDA0, SCL1, SCL2, SDA1, SDA2 = GND or V <sub>VL</sub> (Note 5)	-1		+1	μΑ
Off-Input Leakage Current	INOFF	$EN = V_L, V_L = +3.6V, V_{IN} = V_L - 0.2V$	-1		+1	μΑ
CONTROL LOGIC (SEL, EN)						
Input Voltage Low	V <sub>ILL</sub> OG				0.33 x V <sub>L</sub>	V
Input Voltage High	VIHLOG		0.66 x V <sub>L</sub>			V
Input Logic Hysteresis	V <sub>HYST</sub>			75		mV
Input Leakage Current	IINLEK	$V_{CC} = +5.5V$ , $V_{L} = +3.6V$ , $V_{IN} = 0$ or $V_{L}$	-1		+1	μΑ
ESD PROTECTION						
ESD Protection		Human Body Model; R1, G1, B1, R2, G2, B2, SDA1, SCL1, SDA2, SCL2, H1, V1		±15		kV
		Human Body Model; all other pins		±10		

#### **AC ELECTRICAL CHARACTERISTICS**

 $(V_{CC} = +5.0V \pm 10\%, V_L = +2V \text{ to } +5.5V, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted.}$  Typical values are at  $V_{CC} = +5.0V, V_L = +3.3V \text{ and } T_A = +25^{\circ}C.)$  (Note 3)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Bandwidth	f <sub>MAX</sub>	$R_S = R_L = 50\Omega$		1		GHz
Insertion Loss	ILOS	$f = 1MHz$ , $R_S = R_L = 50\Omega$ , Figure 1		0.6		dB
Crosstalk	V <sub>C</sub> T	$f = 50MHz$ , $R_S = R_L = 50\Omega$ , Figure 1		-40		dB
Off-Capacitance	Coff	f = 250MHz		4.5		рF
On-Capacitance	Con	f = 250MHz		6.4		рF





#### **TIMING CHARACTERISTICS**

 $(V_{CC} = +5.0V \pm 10\%, V_L = +2V \text{ to } +5.5V, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted.}$  Typical values are at  $V_{CC} = +5.0V, V_L = +3.3V$  and  $T_A = +25^{\circ}C.)$  (Note 3)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
RGB ANALOG SWITCHES						
Output Skew Between Ports	tskew	Skew between any two ports: R_, G_, B_, Figure 2		50		ps
HV BUFFER						
Propagation Delay	tpD	$R_L = 1k\Omega$ , $C_L = 10pF$ , Figure 2		15		ns

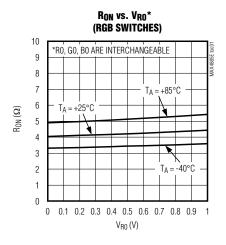
**Note 3:** All devices are 100% production tested at  $T_A = +25$ °C. Specifications over the full temperature range are guaranteed by design.

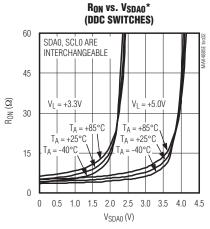
Note 4: On-resistance guarantees the low-static logic level.

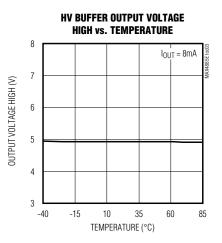
Note 5: SDA\_, SCL\_ off-input leakage current guarantees the high-static logic level.

# Typical Operating Characteristics

( $V_{CC}$  = +5.0V,  $V_{L}$  = +3.3V and  $T_{A}$  = +25 $^{\circ}C$ , unless otherwise noted.)



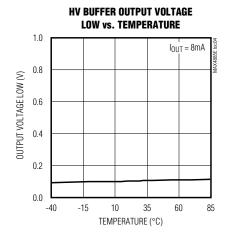


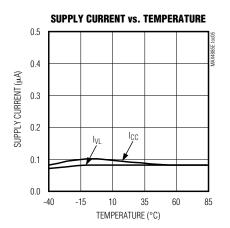


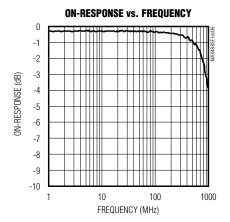


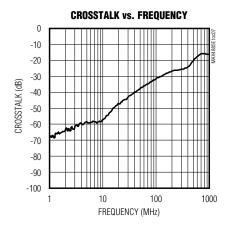
## **Typical Operating Characteristics (continued)**

( $V_{CC} = +5.0V$ ,  $V_L = +3.3V$  and  $T_A = +25$ °C, unless otherwise noted.)











## **Timing Circuits/Timing Diagrams**

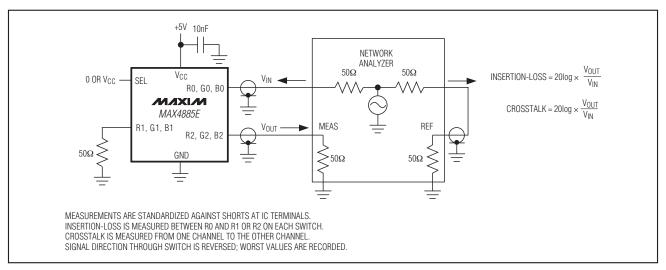


Figure 1. Insertion-Loss and Crosstalk

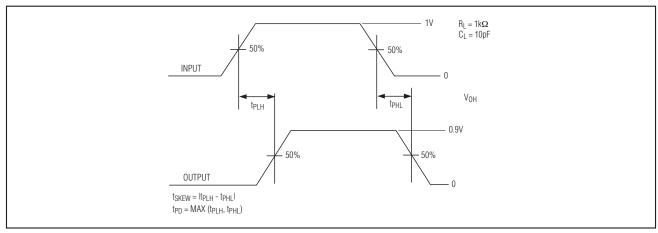


Figure 2. Propagation Delay and Skew Waveforms



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# Ultra-Low Capacitance 1:2 VGA Switch with ±15kV ESD

### **Pin Description**

PIN	NAME	FUNCTION
1	SDA0	SDA I/O
2	SCL0	SCL I/O
3	R0	RGB Analog I/O
4	G0	RGB Analog I/O
5	B0	RGB Analog I/O
6	H0	Horizontal Sync Input
7	VO	Vertical Sync Input
8	Vcc	Supply Voltage. $V_{CC} = +5.0V \pm 10\%$ . Bypass $V_{CC}$ to GND with a $0.1\mu F$ or larger ceramic capacitor.
9	VL	Supply Voltage. $+2V \le V_L \le +5.5V$ . Bypass $V_L$ to GND with a $0.1\mu F$ or larger ceramic capacitor.
10	GND	Ground
11	H1	Horizontal Sync Output*
12	V1	Vertical Sync Output*
13	B2	RGB Analog I/O*
14	B1	RGB Analog I/O*
15	G2	RGB Analog I/O*
16	G1	RGB Analog I/O*
17	R2	RGB Analog I/O*
18	R1	RGB Analog I/O*
19	SCL2	SCL I/O*
20	SCL1	SCL I/O*
21	SDA2	SDA I/O*
22	SDA1	SDA I/O*
23	EN	Enable Input. Drive EN high for normal operation. Drive EN low to disable the device.
24	SEL	Select Input. Logic input for switching RGB and DDC swiches.
_	EP	Exposed Pad. Connect exposed pad to ground or leave unconnected.

<sup>\*</sup>Terminal as ±15kV ESD protection—Human Body Model.

### **Detailed Description**

The MAX4885E integrates high-bandwidth analog switches and level-translating buffers to implement a complete 1:2 multiplexer for VGA signals. The device provides switching for RGB, HSYNC, VSYNC, SDA\_ and SCL\_ signals.

The HSYNC and VSYNC inputs feature level-shifting buffers to support TTL output logic levels from low-voltage graphics controllers. These buffered switches may be driven from as little as +2.0V up to +5.5V. RGB signals are routed with the same high-performance analog switches, and SDA\_, SCL\_ signals are voltage clamped to a diode drop less than V<sub>L</sub>. Voltage clamping provides protection and compatibility with SDA\_ and SCL\_ signals and low-voltage ASICs. In keyboard/video/

mouse (KVM) applications,  $V_L$  is normally set to +5V because low-voltage clamping is not required, as specified by the VESA standard.

Drive EN logic-low to shut down the MAX4885E. In shut-down mode, all switches are high impedance, providing high-signal rejection. The RGB, HSYNC, VSYNC, SDA\_, and SCL\_ outputs are ESD protected to  $\pm 15 \text{kV}$  by the Human Body Model.

#### **RGB Switches**

The MAX4885E provides three SPDT high-bandwidth switches to route standard VGA R, G, and B signals (see Table 1). The R, G, and B analog switches are identical, and any of the three switches can be used to route red, green, or blue video signals.





#### **Table 1. RGB Truth Table**

EN	SEL	FUNCTION	
1	0	R0 to R1 G0 to G1 B0 to B1	
1	1	R0 to R2 G0 to G2 B0 to B2	
0	X	R_, B_, and G_, high impedance	

X = Don't care.

#### **Table 2. HV Truth Table**

EN	FUNCTION
0	H_, V_ = 0

X = Don't care

#### **Table 3. DDC Truth Table**

EN	SEL	FUNCTION
1	0	SDA0 to SDA1 SCL0 to SCL1
1	1	SDA0 to SDA2 SCL0 to SCL2
0	Χ	SDA_, SCL_, high impedance

X = Don't care.

#### Horizontal/Vertical Sync Level Shifter

HSYNC/VSYNC are buffered to provide level shifting and drive capability to meet the VESA specification.

#### Display-Data Channel Multiplexer

The MAX4885E provides two voltage-clamped switches to route DDC signals (see Table 3). Each switch clamps signals to a diode drop less than the voltage applied on V<sub>L</sub>. Supply +3.3V on V<sub>L</sub> to provide voltage clamping for VESA I<sup>2</sup>C-compatible signals. If voltage clamping is not required, connect V<sub>L</sub> to V<sub>CC</sub>. The SDA\_ and SCL\_ switches are identical, and each switch can be used to route either SDA\_ and SCL\_ signals.

#### **ESD Protection**

As with all Maxim devices, ESD-protection structures are incorporated on all pins to protect against electrostatic discharges encountered during handling and assembly. Additionally, the MAX4885E is protected to ±15kV on RGB, HSYNC, VSYNC, SDA\_ and SCL\_

outputs by the Human Body Model (HBM). See the *Pin Description* section. For optimum ESD performance, bypass each VCC pin to ground with a  $0.1\mu F$  or larger ceramic capacitor.

#### Human Body Model (HBM)

Several ESD testing standards exist for measuring the robustness of ESD structures. The ESD protection of the MAX4885E is characterized with the Human Body Model. Figure 3 shows the model used to simulate an ESD event resulting from contact with the human body. The model consists of a 100pF storage capacitor that is charged to a high voltage, then discharged through a 1.5k $\Omega$  resistor. Figure 4 shows the current waveform when the storage capacitor is discharged into a low impedance.

#### **ESD Test Conditions**

ESD performance depends on a variety of conditions. Please contact Maxim for a reliability report documenting test setup, methodology, and results.

### **Applications Information**

The MAX4885E provides the level shifting necessary to drive two standard VGA ports from a graphics controller as low as +2.2V. Internal buffers drive the HSYNC and VSYNC signals to VGA standard TTL levels. The DDC multiplexer provides level shifting by clamping signals to a diode drop less than VL (see the Typical Operating Circuit). Connect VL to +3.3V for normal operation, or to VCC to disable voltage clamping for DDC signals.

#### **Power-Supply Decoupling**

Bypass each VCC pin and VL to ground with a  $0.1\mu F$  or larger ceramic capacitor as close as possible to the device.

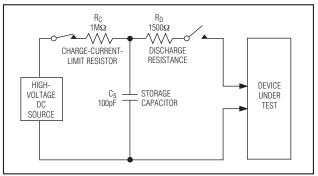
#### **PCB Layout**

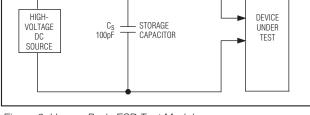
High-speed switches such as the MAX4885E require proper PCB layout for optimum performance. Ensure that impedance-controlled PCB traces for high-speed signals are matched in length and as short as possible. Connect the exposed pad to a solid ground plane.

Chip Information

PROCESS: BICMOS





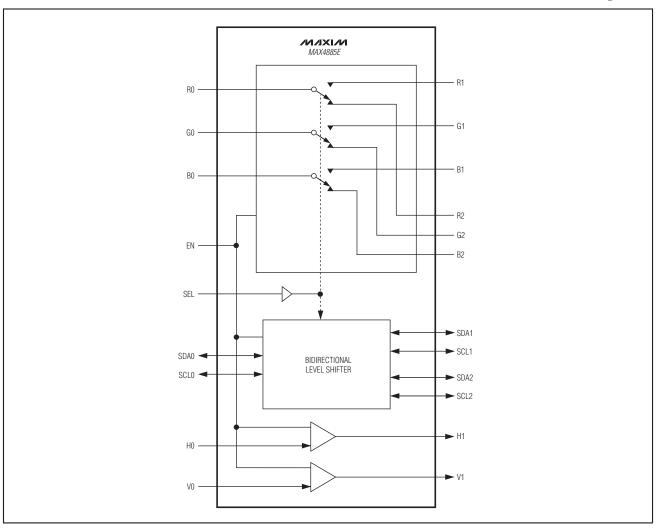


PEAK-TO-PEAK RINGING (NOT DRAWN TO SCALE) I<sub>P</sub> 100% 90% AMPERES 36.8% 10% TIME  $t_{RL}$ t<sub>DL</sub> CURRENT WAVEFORM

Figure 3. Human Body ESD Test Model

Figure 4. HBM Discharge Current Waveform

## **Functional Diagram**





## **Package Information**

For the latest package outline information and land patterns, go to www.maxim-ic.com/packages

PACKAGE TYPE	PACKAGE CODE	DOCUMENT NO.
24 TQFN-EP	T2444-4	<u>21-0139</u>

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